TE Internal #: 2-2347090-1

LGA Sockets, LGA 4677, 4677 Position, Surface Mount - Solder Ball,

Grid Spacing .81389 x .9398 mm

View on TE.com >



Connectors > Socket Connectors > IC Sockets > LGA Sockets











IC Socket Type: **LGA 4677**Number of Positions: **4677**

Contact Mating Area Plating Material Thickness: [30 µin]

Termination Method to Printed Circuit Board: Surface Mount - Solder Ball

Grid Spacing: .81389 x .9398 mm

Features

Product Type Features

Connector System	Board-to-Component
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	4677
Grid Spacing	.81389 x .9398 mm

Body Features

Frame Style	Square	
,	'	

Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 4677
	30 µin
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
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Housing Features	
Housing Material	LCP (Liquid Crystal Polymer)
Housing Color	Black
Usage Conditions	
Operating Temperature Range	-40 – 100 °C
Operation/Application	
Circuit Application	Signal

Industry Standards

Packaging Features

Tray Color	Black
Packaging Method	Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



TE Part # 1-2351052-2 LGA4677 E1B CARRIER ASSY



TE Part # 1-2351052-5 LGA4677 E1A CARRIER ASSY



TE Part # 1-2351052-6 LGA4677 E1C CARRIER ASSY



TE Part # 1-2351053-2 LGA4677 SOCKET COVER



TE Part # 2-2351050-4 LGA4677 TFLM ASSY,W/O COVER



TE Part # 2-2351050-5 LGA4677 TFLM ASSY,W/ COVER

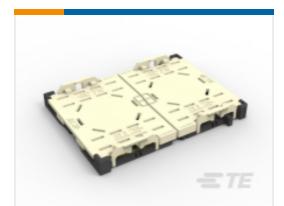


TE Part # 2351051-1 LGA4677 BACKPLATE ASSY,SHORT STUD



TE Part # 2351051-2 LGA4677 BACKPLATE ASSY,LONG STUD

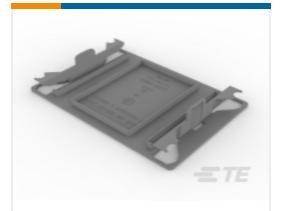
Customers Also Bought



TE Part #1-2324271-3 RIGHT SEGMENT LGA4189-4 SOCKETP4 FOR ODM



TE Part #1-2324271-4 LEFT SEGMENT LGA4189-4 SOCKET-P4 FOR ODM



TE Part #2-2330553-1 SOCKET P4/P5 DUST COVER, LGA4189



TE Part #1-2351053-2 LGA4677 SOCKET COVER



TE Part #2-2330550-1 SOCKET P4 BOLSTER PLATE ASSY, W /O COVER



TE Part #2-2351050-4 LGA4677 TFLM ASSY,W/O COVER



TE Part #2351051-1 LGA4677 BACKPLATE ASSY,SHORT STUD

TE Part #2373624-4 Rcpt Assy,Diecast Housing,PCle Gen 5 LGA Sockets, LGA 4677, 4677 Position, Surface Mount - Solder Ball, Grid Spacing . 81389 x .9398 mm



TE Part #2379420-2

SOCKET E1 TFLM KIT W/ COVER

TE Part #2356580-5

SOCKET P4 TFLM KIT W/ COVER FOR INSPUR

Documents

CAD Files

Customer View Model

ENG_CVM_CVM_2-2347090-1_7.3d_stp.zip

English

Customer View Model

ENG_CVM_CVM_2-2347090-1_7.3d_igs.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-2347090-1_7.2d_dxf.zip

English

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